Features

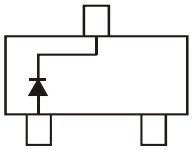
- Ultra-Small Surface Mount Package
- Fast Switching Speed
- For General Purpose Switching Applications
- High Conductance
- **Lead Free/RoHS Compliant (Note 1)**
- **"Green" Device (Note 3 and 4)**

Mechanical Data

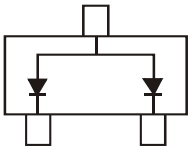
- Case: SOT-523
- Case Material - Molded Plastic. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish)
- Polarity: See Diagrams Below
- Marking Information: See Diagrams Below & Page 2
- Ordering Information: See Page 2
- Weight: 0.002 grams (approximate)

SOT-523

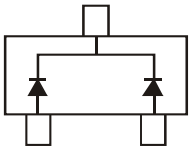
TOP VIEW



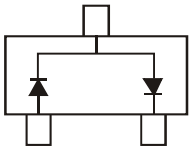
BAS16T Marking: A2



BAW56T Marking: JD



BAV70T Marking: JJ



BAV99T Marking: JE

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V_{RRM} V_{RWM} V_R	85	V
RMS Reverse Voltage		$V_{R(RMS)}$	60	V
Forward Continuous Current (Note 2)	Single Diode Double Diode	I_{FM}	155 75	mA
Repetitive Peak Forward Current		I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I_{FSM}	4.0 1.0 0.5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P_D	150	mW
Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	833	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	85	—	—	V	I_R = 100μA
Forward Voltage	V_F	—	—	0.715 0.855 1.0 1.25	V	I_F = 1.0mA I_F = 10mA I_F = 50mA I_F = 150mA
Leakage Current (Note 5)	I_R	—	—	2.0 100 60 30	μA μA μA nA	V_R = 75V V_R = 75V, T_J = 150°C V_R = 25V, T_J = 150°C V_R = 25V
Total Capacitance	C_T	—	1.5	—	pF	V_R = 0, f = 1.0MHz
Reverse Recovery Time	t_{rr}	—	—	4.0	ns	I_F = I_R = 10mA, I_{rr} = 0.1 x I_R, R_L = 100Ω

Notes:
1. No purposefully added lead.
2. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
4. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.
5. Short duration pulse test used to minimize self-heating effect.

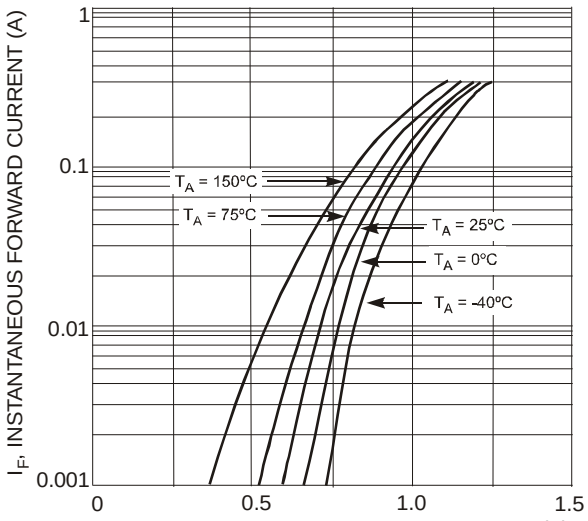


Fig. 1 Typical Forward Characteristics, Per Element

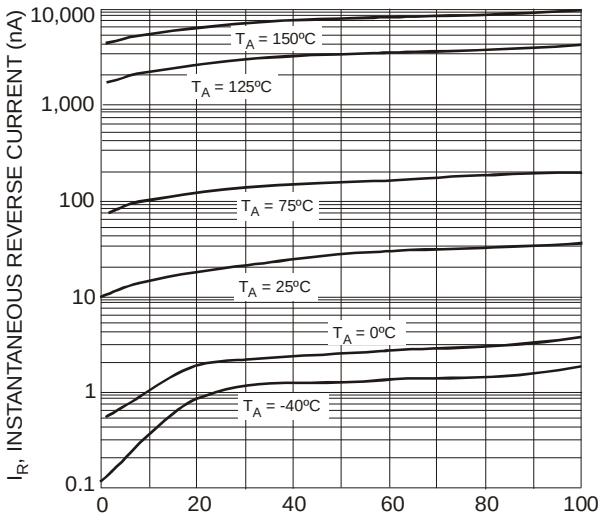


Fig. 2 Typical Reverse Characteristics, Per Element

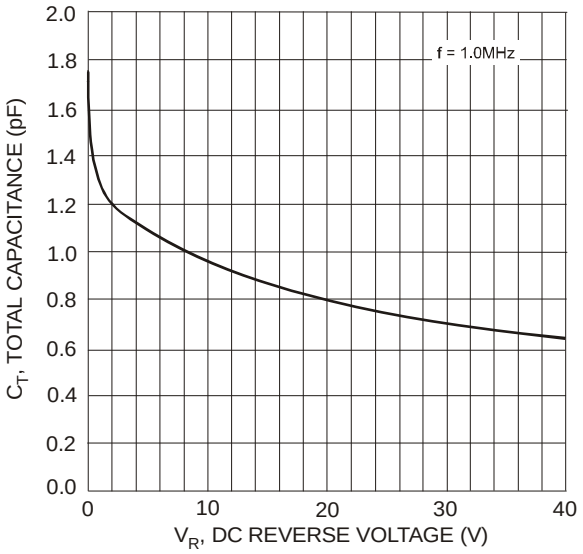


Fig. 3 Total Capacitance vs. Reverse Voltage, Per Element

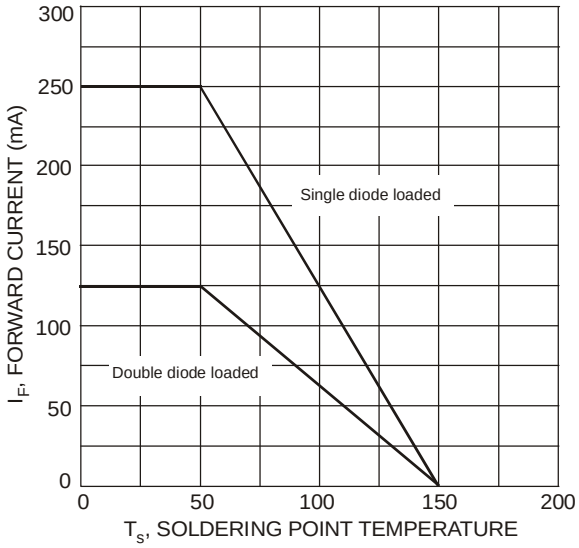


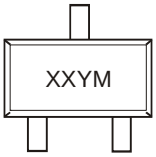
Fig. 4 Current Derating Curve, Total Package

Ordering Information (Note 6)

Part Number	Case	Packaging
BAS16T-7-F	SOT-523	3000/Tape & Reel
BAW56T-7-F	SOT-523	3000/Tape & Reel
BAV70T-7-F	SOT-523	3000/Tape & Reel
BAV99T-7-F	SOT-523	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



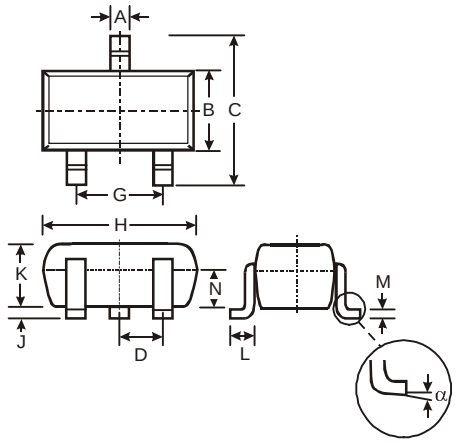
XX = Product Type Marking Code (See Page 1, e.g. A2 = BAS16T)
YM = Date Code Marking
Y = Year (ex: N = 2002)
M = Month (ex: 9 = September)

Date Code Key

Year	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	N	P	R	S	T	U	V	W	X	Y	Z

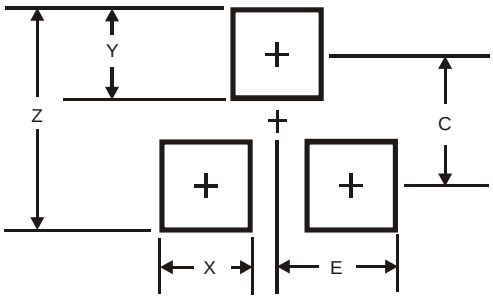
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-523			
Dim	**Min**	**Max**	**Typ**
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7